

PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Byung-Eun PARK	06/08/2007
RECEIVING PARTY DATA	
Name:	University of Seoul Foundation of Industry - Academic Corporation
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Internal Address:	Dongdaemun-gu
City:	Seoul
State/Country:	KOREA, REPUBLIC OF
Postal Code:	130-743
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11721599
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Total Attachments: 2 source=Assign-signed#page1.tif source=Assign-signed#page2.tif	

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TO: 00119146840304

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ASSIGNMENT OF PATENT APPLICATION

Whereas, I, the below named inventor, have invented certain new and useful improvements for an Invention entitled:

Ferroelectric Memory Device And Method Of Manufacturing The Same

for which an application for a United States Letters Patent has been filed.

Whereas, University Of Seoul Foundation Of Industry – Academic Cooperation, a corporation organized under and existing by virtue of the laws of Korea, and having a place of business at University of Seoul 90, Jeonong-dong, Dongdaemun-gu, Seoul 130-743 Korea (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in the same,

Now, therefore, in consideration of the sum of one dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, by these presents, do hereby sell, assign and transfer unto said Assignee the full and exclusive right, title and interest, together with all rights of priority, to the said Invention in the United States and the entire world and the entire right, title, and interest in and to any and all Letters Patent which may be granted therefore in the United States and the entire world, and all divisional, continuing, substitute, and reissue applications for Letters Patent which have been or shall be filed in the United States of America or anywhere in the world.

The Assignee is hereby authorized to make application for and to receive Letters Patent for said Invention in the USA and any other country in the world in its own name, or in our names, at its election, and consistent with applicable law.

I agree that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, in order to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all original, divisional, continuing, substitute, reissue patent applications on said invention; execute all rightful oaths, declarations,

2007-06-13 00:49 FROM:

TO:00119146840304

P:21/25

assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said Invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said Invention and for vesting title to said Invention, and all applications for patents, in said Assignee, its successors, assigns and legal representatives.

I hereby authorize and request the U.S. Commissioner of Patents and Trademarks and the Patent Offices of all countries of the world to issue said Letters Patent to said Assignee as the assignee of the entire right, title, and interest in and to the same, for its sole use and behoof; and for the use and behoof of its legal representatives, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by us had this assignment and sale not been made.

Executed by me on the date below indicated beside my signature.

Inventor Name: Byung-Eun PARK
Citizenship: Korca

Residence/mailling address: 302, Chunggrim Villa, 505-15 Mog-dong
Yangchun-gu
Seoul 158-807 Korca

SIGNATURE: Byung Eun Park DATE: June 8, 2007